



MATERIALS REQUIREMENTS

MATERIAL: FR4

THICKNESS: 0.8mm 1.2mm 1.6mm 2.4mm 3.2mm

TOLERANCE: IN A/W IPC-D-300G CLASS 1 OTHER +/-

BOW & TWIST: IN A/W IPC-D-300G CLASS 1 AS SHOWN

COPPER THICKNESS (FINISHED)

OUTER: 18um 35um 70um

INNER SIGNAL: 18um 35um 70um

INNER PLANE: 18um 35um 70um

COPPER LAYER STRUCTURE

LAYER NUMBER	DESCRIPTION	GERBER EXT.
1	COMPONENT SIDE	GTL
2	SOLDER SIDE	GBL

SPECIAL CONSIDERATIONS

SEE .REP FILE FOR FULL GERBER INFO.

DRILLING AND FINISH REQUIREMENTS

VIEWED FROM: COMPONENT SIDE SOLDER SIDE

REFERENCE: AS SHOWN PATTERN MASTER LIST NC DRILL FILES

PTH MINIMUM COPPER THICKNESS: 20um OTHER

NPPTH: TENTED PADS REMOVED REMOVE PADS

2ND DRILL BOTH AS SHOWN NONE

VIAS: TENTED COMPONENT SIDE SOLDER SIDE

LEGEND & SCREEN PRINT: NONE COMPONENT SOLDER

COLOR: YELLOW WHITE OTHER

SOLDER RESIST: LIQUID PHOTOIMAGEABLE SCREEN PRINT

FINISH: MATTE GLOSS EITHER

COLOUR: RED GREEN YELLOW BLUE OTHER

TRACK FINISH: SELECTIVE SOLDER (HASL) REFLOW SOLDER

0.1um - 0.2um ELECTROLESS GOLD OVER 3um NICKEL

IMMERSION GOLD OTHER

ADDITIONAL NOTES:

HITEX (UK) LTD. Sir William Lyons Road Coventry CV4 7EZ ENGLAND	ENGINEER:	A. DAVISON		TITLE:	MBED PROTOTYPING BASE BOARD	
	PCB DESIGNER:	A. DAVISON				
	DATE:	04/06/2010	PART NO.:	HIT044 MBED BB	REV.:	A1
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